

30V N-Channel Enhancement Mode MOSFET

Description

The 50N03 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 30V$ $I_D = 50A$

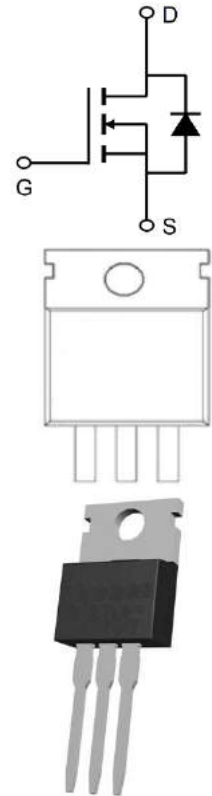
$R_{DS(ON)} < 18m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



Absolute Maximum Ratings (TC=25°C unless otherwise specified)

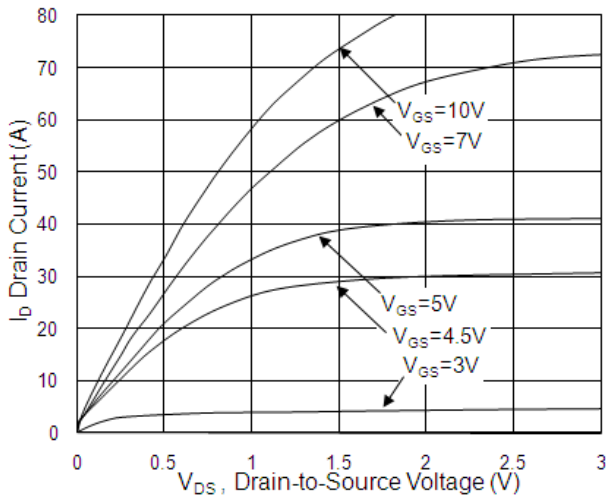
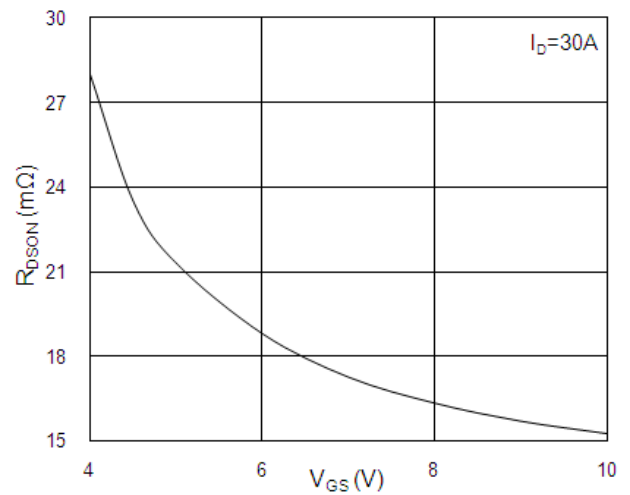
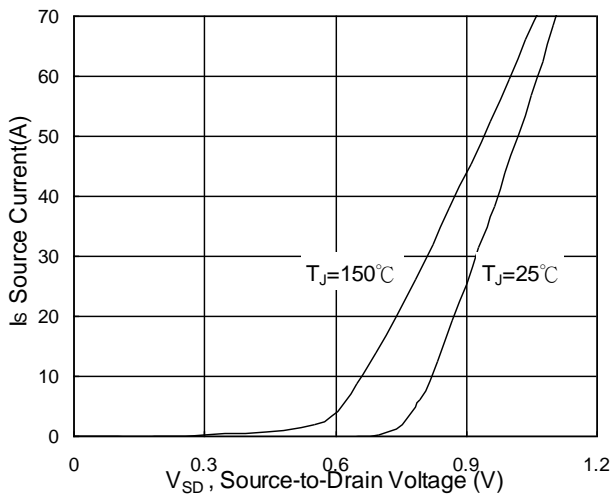
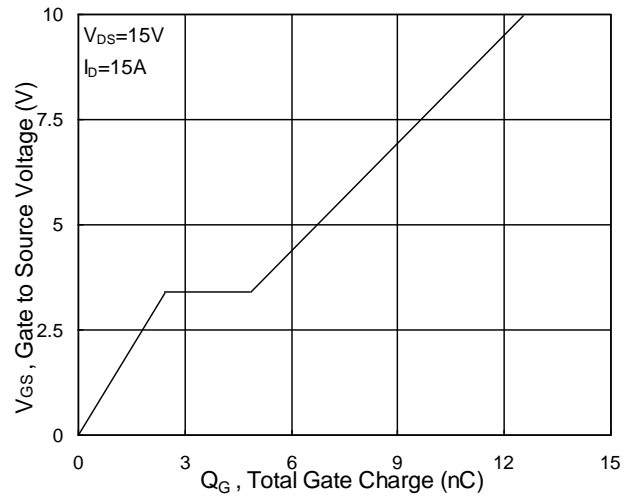
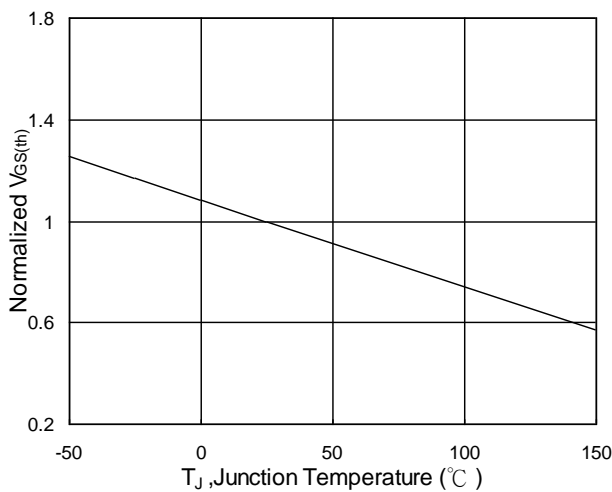
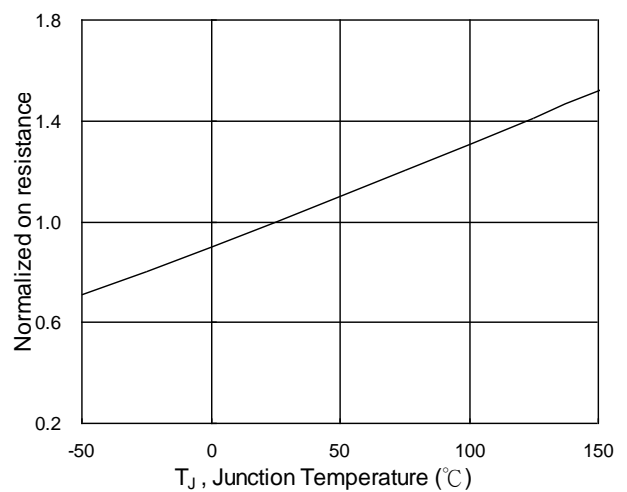
Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	30	V
VGS	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	50	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	24	A
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	8.2	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6.5	A
IDM	Pulsed Drain Current ²	75	A
EAS	Single Pulse Avalanche Energy ³	22	mJ
IAS	Avalanche Current	21	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	41	W
$P_D@T_A=25^\circ C$	Total Power Dissipation ⁴	2	W
TSTG	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-ambient (Steady State) ¹	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	3	°C/W

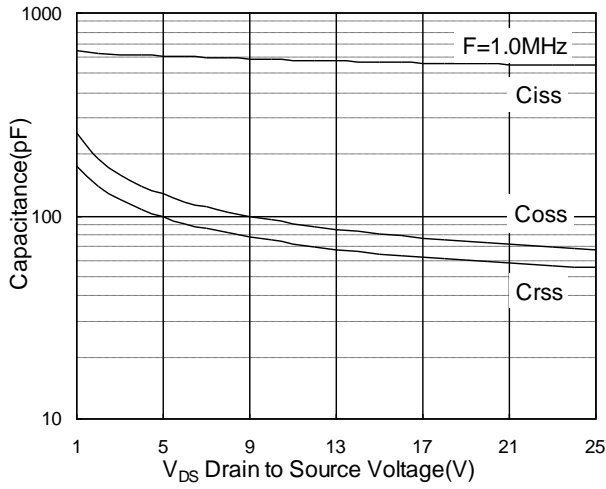
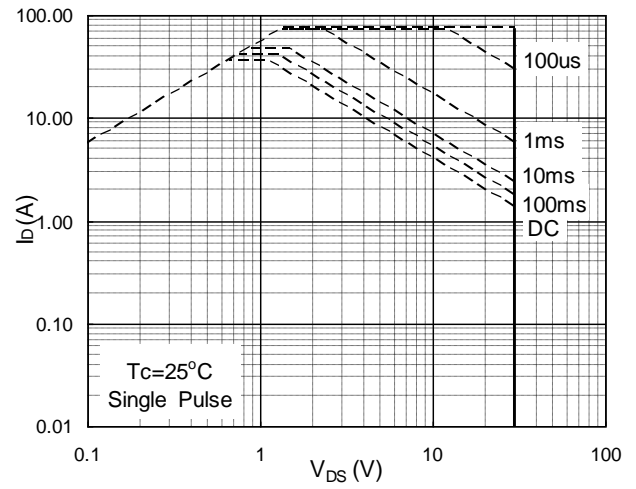
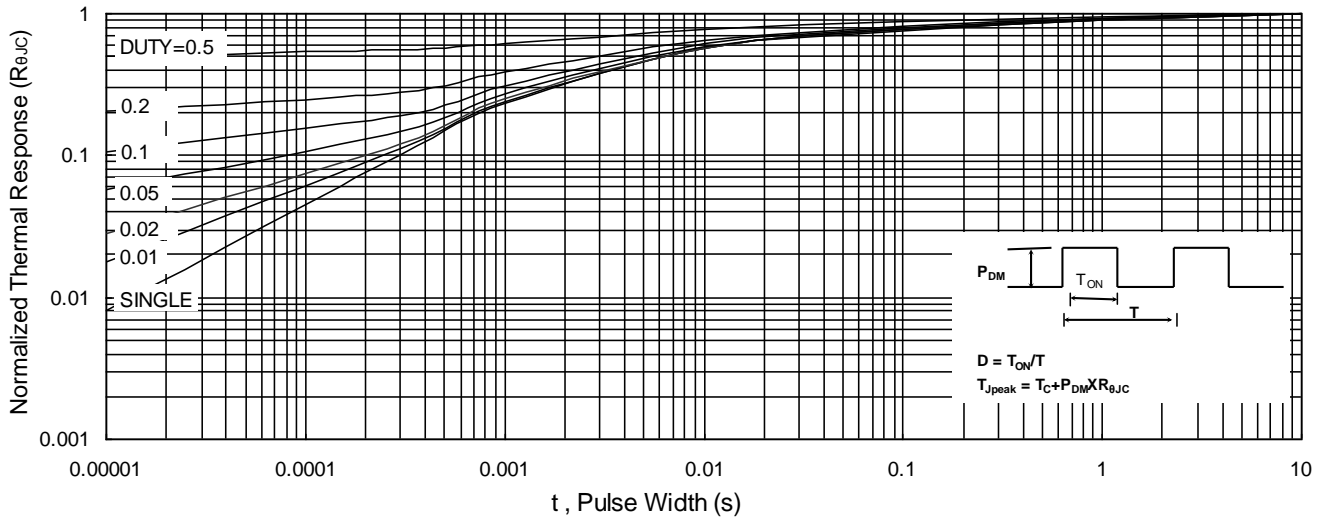
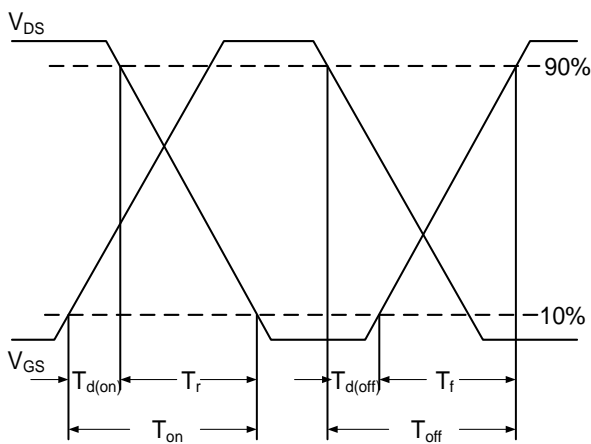
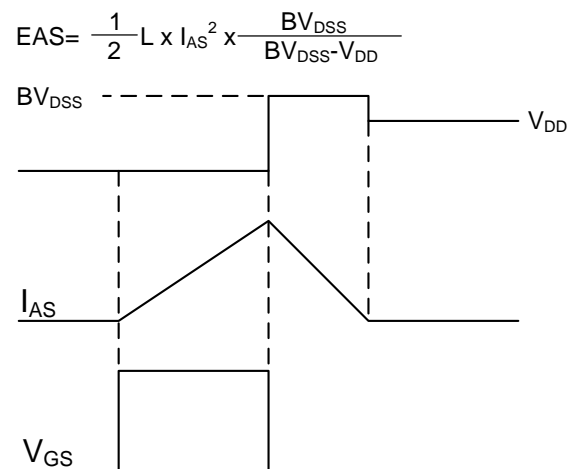
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Electrical Characteristics (at $T_J=25^\circ\text{C}$ unless otherwise specified)

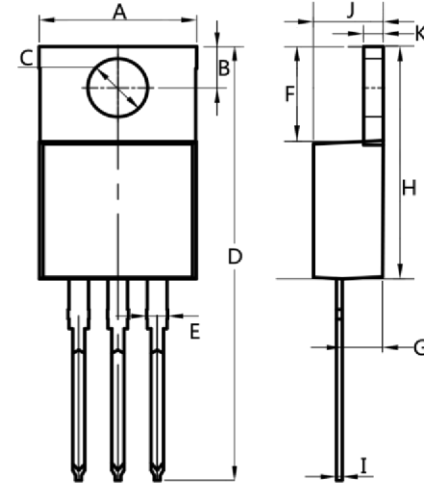
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.024	---	$V/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=30A$	---	---	18	m Ω
		$V_{GS}=4.5V, I_D=15A$	---	---	30	
VGS(th)	Gate Threshold Voltage		1.2	---	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient	$V_{GS}=V_{DS}, I_D=250\mu A$	---	-3.4	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=15V, I_D=30A$	---	19	---	S
Rg	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2.5	---	Ω
Qg	Total Gate Charge (4.5V)		---	6.2	---	nC
Qgs	Gate-Source Charge	$V_{DS}=15V, V_{GS}=4.5V, I_D=15A$	---	2.4	---	
Qgd	Gate-Drain Charge		---	2.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V,$ $R_G=3.3\Omega,$ $I_D=15A$	---	3	---	ns
Tr	Rise Time		---	7.6	---	
Td(off)	Turn-Off Delay Time		---	21	---	
Tf	Fall Time		---	4	---	
Ciss	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	572	---	μF
Coss	Output Capacitance		---	81	---	
Crss	Reverse Transfer Capacitance		---	65	---	
IS	Continuous Source Current ^{1,5}	$V_G=V_D=0V, \text{Force Current}$	---	---	37	A
ISM	Pulsed Source Current ^{2,5}		---	---	75	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1.2	V
trr	Reverse Recovery Time	$I_F=15A, di/dt=100A/\mu s,$	---	17	---	nS
Qrr	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	3	---	nC

Note :

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The EAS data shows Max. rating. The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=21A$
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

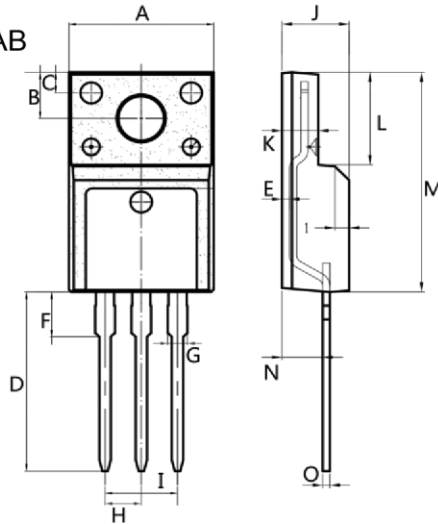
Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. G-S Voltage

Fig.3 Forward Characteristics Of Reverse

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs. T_J

Fig.6 Normalized $R_{DS(on)}$ vs. T_J

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Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

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TO-220AB


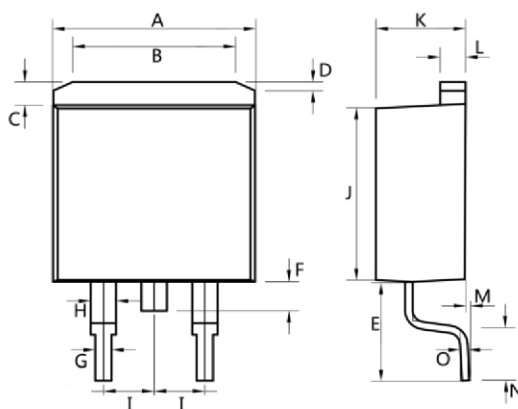
Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter

ITO-220AB


Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60

All Dimensions in millimeter

TO-263


Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter